Inventec Data Center Solutions

Solrock

Highest Density Performance 2U 4Node Compute Server

Highlights

- **Efficient Dual Sockets per node with 3rd Gen Intel® Xeon® Scalable Processors**
- **New Generation Platform with PCIe Gen4 Technology**
- **8x LFF HDDs/ 12x NVMe SSDs within a system**
- **Easy Service and Maintenance**

Solrock is a highly efficient and ultra-dense 2U4N rackmount server system powered by dual 3rd Gen Intel® Xeon® Scalable processors. With multi-node design, Solrock not only features unparallel computing power as well as energy-saving design, but also an impressive TCO reduction. Solrock brings the flexibility and scalability in its 2U four-node high density enclosure; it can be easily scaled out to perform high performance computing and fulfill independent workload deployment. Solrock is a robust solution for various market demands such as virtualization, machine learning, hyperconverged applications and intensive cloud computing.

Innovation for a Range of HPC Workloads

Solrock comprises of four high performance nodes, each node supporting dual 3rd Gen Intel Xeon Scalable processors, with TDP up to 165W and has up to 4TB of DDR4 memory. In addition, it supports new Intel Optane persistent memory 200 series modules, including up to 1.6x higher memory bandwidth and up to 2.66x higher memory capability versus prior generation. The platform also provides a balanced architecture with built-in acceleration and advanced security capabilities which are designed to handle the most demanding workload requirements.

Virtualization

Machine Learning

High Density Computing

Front View

Rear View

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Superior Scalability and Flexibility

Solrock offers a variety of hot-pluggable hybrid flash array choices with modular front drive bay design, ranging from 8x 3.5” LFF HDDs to 12x NVMe SSDs in a system. Each node possesses efficient scale-out capacity by hosting 1x PCIe x16 slot and 1x OCP 3.0 slot, Solrock is well positioned to cater to the most demanding application requirements.

Enhanced Serviceability and Reliability

To increase serviceability and reliability, Solrock supports three dual rotor fans per node and two hot-pluggable power supplies at the rear as well as removing an entire node while the rest of the system functions unaffected. With optimized TCO, Solrock’s multi-node high density design provides the highest efficiency of massive parallel computing for HPC applications.

Positioning	High Performance Computing (HPC)
Form Factor	2U4N rack-mounted W x H x D : 447.0 x 87.0mm x 866.0mm (17.59 x 3.07 x 34.09 inch)
Processor (per node)	Dual Socket; 3rd Gen Intel® Xeon® Scalable processors TDP up to 165W
Memory Slot (per node)	Max. 4TB 16x DDR4 DIMM slots Up to 3200MHz ECC 2DPC DDR4 RDIMM/LRDIMM
Chipset (per node)	Intel® C621A Series Chipset
Disk Drive Bay	**Primary bays:** SKU1 : 8x 3.5” LFF SATA HDD (2x 3.5” HDD per node) SKU2 : 12x NVMe SSDs hot-plug drive (3x NVMe SSDs per node)
Expansion Slot (per node)	**Rear per node:** 1x PCIe Gen4 x16 OCP 3.0 NIC 1x PCIe Gen4 x16 (Low Profile)
Network Controller (per node)	Supporting 10GbE/25GbE OCP 3.0 card
Storage Controller (per node)	**Onboard per node:** 8x SATA3 6Gb/s port
System Management (per node)	ASPEED AST2500, IPMI2.0 Complaint. 1 x management RJ45 port with 100/1000 Mbps
TPM (per node)	TPM2.0 (optional)
Power Supply	1+1 CRPS PSU, 2400W (110-220Vac) Platinum
Fan	N+1 redundancy 3x 4056 dual rotor fans per node (12x 4056 dual rotor fans per system)

About Inventec Data Center Solutions (Inventec EBG)

Inventec Data Center Solutions (Inventec EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems in Inventec Corporation. Over decades, Inventec EBG has been the key server system supplier of the global branding clients.

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